

TS3A226AE Evaluation Board

This user guide describes the TS3A226AE evaluation module (EVM) usage. This guide contains the EVM schematics, evaluation examples, and bill of materials to evaluate the performance of the TS3A226AE device.

Contents

1	Introduction				
2	EVM Setuup				
	2.1 Boards	2			
	2.2 Setup Procedure	2			
3	Evaluating TS3A226AE				
	3.1 Test with Different Types of Headsets				
4	EVM Schematics				
5					
	List of Figures				
1	TS3A226AE Evaluation board	2			
2 TS3A226AE EVM Schematic					
	List of Tables				
1	TS3A226AE Evaluation Module Signal Connections	2			
2	Bill of Materials	5			

1 Introduction

The TS3A226AE is an audio headset switch that detects 3- or 4-pole 3.5mm accessories. For a 4-pole accessory with a microphone, the TS3A226AE also detects the MIC location and routes the microphone and ground signals automatically. The ground signal is routed through a pair of low-impedance ground FETs ($60m\Omega$ typical), resulting minimal impact on audio cross-talk performance. The autonomous detection feature allows end users to plug in accessories with different audio pole configurations into the mobile device and have them operate properly with no added software control and complexity. The ground FETs of the device are designed to allow FM signal pass-through, making it possible to use the ground line of the headset as an FM antenna in mobile audio application.

The TS3A226AE EVM is an evaluation module for the Texas Instruments TS3A226AE switch and it provides the basic functionality evaluation for the device.



EVM Setuup www.ti.com

2 EVM Setuup

2.1 Boards

One TS3A226AE Evaluation board is provided per EVM kit:



Figure 1. TS3A226AE Evaluation board

Table 1. TS3A226AE Evaluation Module Signal Connections

	Туре	Description	Purpose
J3	SMA Connector	FM signal output	If GND is used for FM signal transmission, FM receiver can be connected to this connector for sensitivity test.
J4	RCA Connector	For MIC signal output	Can be connected to Codec for microphone testing.
J5	RCA Connector	RING1 connection	Can be connected to Audio Amplifier (right channel) output for audio testing.
J6	RCA Connector	TIP connection	Can be connected to Audio Amplifier (left channel) output for audio testing.
J7	Audio Jack Connector	Audio Jack for Headset plug in	Plug in different Headset for TS3A226AE function verification

Test Point headers are placed throughout the board to provide testing capability for each pin of the device and are labeled with the corresponding pin name beside the header pins.

2.2 Setup Procedure

2.2.1 Equipment Required

- Power supply which can provide 2.6V to 4.7V
- Multi-meter

2.2.2 Power up

To provide the VDD to the TS3A226AE. Add the jumper for J1 and J2.



www.ti.com Evaluating TS3A226AE

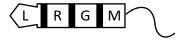
External power supply input are supplied to the VDD test point (TP6) for VDD and GND test points (TP12) for GND.

3 Evaluating TS3A226AE

3.1 Test with Different Types of Headsets

To evaluate the capability of headset detection for TS3A226AE, plug in different types of headsets (4-pole standard, 4-pole OMTP, or regular TRS) to the headset jack J7, and check the detection result.

(1) 4-Pole Standard/ North American Headsets:



If a 4-pole standard/North American headset is plugged-in, below table can be used to check the detection result by measuring the resistor through the hand multi-meter.

	Negative Pole	Positive Pole	Measured Value(Ω)
	TP13(MICP)	TP15(SLEEVE)	≤10
TEST POINTS	TP13(MICP)	TP16(RING2)	>1K
TEST FOINTS	TP21(GNDA)	TP15(SLEEVE)	>1K
	TP12(GNDB)	TP16(RING2)	≤2

(2) 4-Pole OMTP Headsets:



If a 4-pole OMTP headset is plugged-in, below table can be used to check the detection result by measuring the resistor through the hand multi-meter.

	Negative Pole	Positive Pole	Measured Value(Ω)
	TP13(MICP)	TP15(SLEEVE)	>1K
TEST POINTS	TP13(MICP)	TP16(RING2)	≤10
TEST FOINTS	TP21(GNDA)	TP15(SLEEVE)	≤2
	TP12(GNDB)	TP16(RING2)	>1K

(3) RS Audio Headset:



If a regular TRS headset without integrated microphone is plugged-in, below table can be used to check the detection result by measuring the resistor through the hand multi-meter.

	Negative Pole	Positive Pole	Measured Value(Ω)
	TP13(MICP)	TP15(SLEEVE)	<20
TECT DOINTS	TP13(MICP)	TP16(RING2)	<20
TEST POINTS	TP21(GNDA)	TP15(SLEEVE)	≤2
	TP12(GNDB)	TP16(RING2)	≤2

Note: These measured resistor values cannot be used to check the Switch R_{ON} since the multi-meter has the internal output resistor.



EVM Schematics www.ti.com

4 EVM Schematics

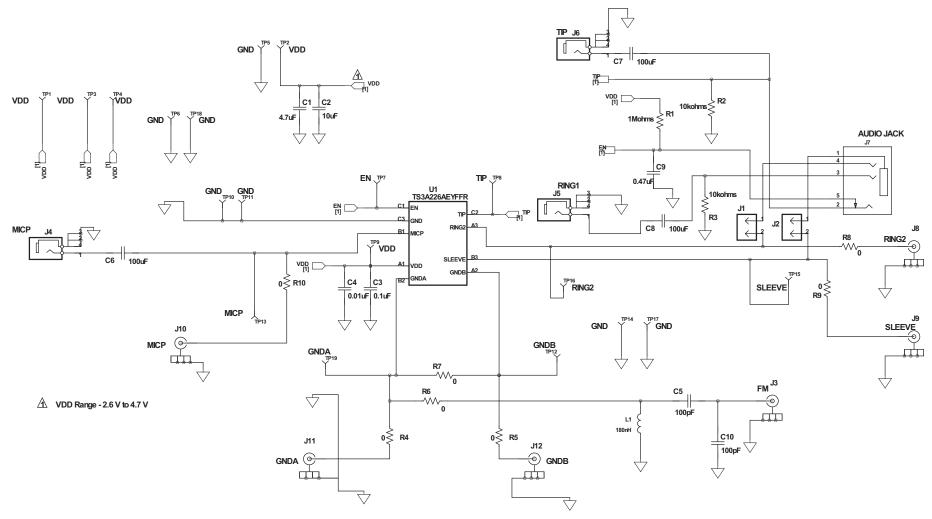


Figure 2. TS3A226AE EVM Schematic



www.ti.com Bill of Materials

5 Bill of Materials

Table 2. Bill of Materials

Count	RefDes	Value	Description	Size	Part Number
1	C1	4.7 μF	Capacitor, Ceramic, Chip, 16V, X7R, ±10%	603	STD
1	C2	10 μF	Capacitor, Ceramic Chip, 16V,X7R, ±10%	1206	STD
1	C3	0.1 μF	Capacitor, Ceramic Chip,16V, X7R, ±10%	402	STD
1	C4	0.01 μF	Capacitor, Ceramic Chip,16V, X7R, ±10%	402	STD
2	C5, C10	100pF	Capacitor, Ceramic, Chip,10V, X7R, ±10%	603	STD
3	C6, C7, C8	100 μF	Capacitor, Ceramic Chip, 10V,X5R, ±10%	1210	STD
1	C9	0.47 μF	Capacitor, Ceramic, Chip, 10V, X7R, ±10%	603	STD
2	J1, J2	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN
1	J3	32K141-40ML5	Connector, SMA, Straight, 50 Ohm, DC to 12.4 GHz	7.6X7.6 mm	32K141-40ML5
3	J4, J5, J6	RCA,161-0350-E	Connector, Phono Jack 3.6 mm, Right Angle	0.571 x 0.471 inch	161-0350-E
1	J7	SJ-43515TS-SMT	Connector, Audio Stereo Jack 3.5 mm	5x17.5 mm	SJ-43515TS- SMT
0(1)	J8, J9, J10, J11, J12	32K141-40ML5	Connector, SMA, Straight, 50 Ohm, DC to 12.4 GHz	7.6X7.6 mm	32K141-40ML5
1	L1	180 nH	Inductor, SMT, 180nH,5%,140mA,2.2ohms, 100MHz 25Q-Factor,SRF with 1300MHz	603	LQW18ANR18J 00D
1	R1	1 Mohms	Resistor, Chip, 1/16W, ±5%	603	STD
2	R2, R3	10 kohms	Resistor, Chip, 1/16W, ±5%	603	STD
0 ⁽¹⁾	R4, R5, R8, R9, R10	0	Resistor, Chip, 1/16W,±5%	201	STD
2	R6, R7	0	Resistor, Chip, 1/16W,±5%	201	STD
19	TP1-TP19	PEC01SAAN	CONN HEADER .100 SINGL STR 1POS	0.100 inch x 1	PEC01SAAN

⁽¹⁾ The count with '0' means no assembly.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Products	Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity